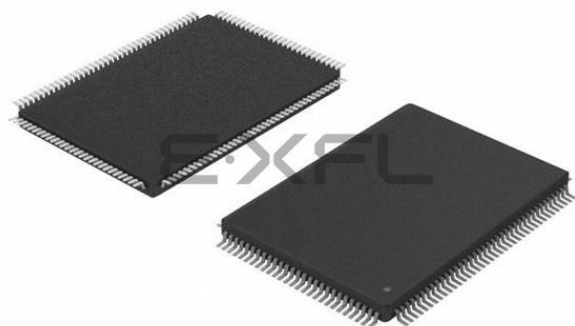




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Details

Product Status	Active
Core Processor	56800E
Core Size	16-Bit
Speed	60MHz
Connectivity	CANbus, EBI/EMI, SCI, SPI
Peripherals	POR, PWM, Temp Sensor, WDT
Number of I/O	49
Program Memory Size	256KB (128K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 16
Voltage - Supply (Vcc/Vdd)	2.25V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc56f8355mfge

Table 2-2 Signal and Package Information for the 128-Pin LQFP (Continued)

Signal Name	Pin No.	Type	State During Reset	Signal Description
INDEX0 (TA2) (GPOPC6)	1	Schmitt Input Schmitt Input/Output Schmitt Input/Output	Input, pullup enabled	Index — Quadrature Decoder 0, INDEX input TA2 — Timer A, Channel 2 Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is INDEX0. To deactivate the internal pullup resistor, clear bit 6 of the GPIOC_PUR register.
HOME0 (TA3) (GPIOC7)	2	Schmitt Input Schmitt Input/Output Schmitt Input/Output	Input, pullup enabled	Home — Quadrature Decoder 0, HOME input TA3 — Timer A, Channel 3 Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is HOME0. To deactivate the internal pullup resistor, clear bit 7 of the GPIOC_PUR register.
SCLK0 (GPIOE4)	124	Schmitt Input/Output Schmitt Input/Output	Input, pullup enabled	SPI 0 Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. Port E GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is SCLK0. To deactivate the internal pullup resistor, clear bit 4 in the GPIOE_PUR register.

Table 2-2 Signal and Package Information for the 128-Pin LQFP (Continued)

Signal Name	Pin No.	Type	State During Reset	Signal Description
PHASEA1 (TB0) (SCLK1) (GPIOC0)	9	Schmitt Input Schmitt Input/Output Schmitt Input/Output Schmitt Input/Output	Input, pullup enabled	Phase A1 — Quadrature Decoder 1, PHASEA input for decoder 1. TB0 — Timer B, Channel 0 SPI 1 Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. To activate the SPI function, set the PHSA_ALT bit in the SIM_GPS register. For details, see Part 6.5.8. Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. In the 56F8355, the default state after reset is PHASEA1. In the 56F8155, the default state is not one of the functions offered and must be reconfigured. To deactivate the internal pullup resistor, clear bit 0 in the GPIOC_PUR register.
PHASEB1 (TB1) (MOSI1) (GPIOC1)	10	Schmitt Input Schmitt Input/Output Schmitt Input/Output Schmitt Input/Output	Input, pullup enabled	Phase B1 — Quadrature Decoder 1, PHASEB input for decoder 1. TB1 — Timer B, Channel 1 SPI 1 Master Out/Slave In — This serial data pin is an output from a master device and an input to a slave device. The master device places data on the MOSI line a half-cycle before the clock edge the slave device uses to latch the data. To activate the SPI function, set the PHSB_ALT bit in the SIM_GPS register. For details, see Part 6.5.8. Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. In the 56F8355, the default state after reset is PHASEB1. In the 56F8155, the default state is not one of the functions offered and must be reconfigured. To deactivate the internal pullup resistor, clear bit 1 in the GPIOC_PUR register.

Part 3 On-Chip Clock Synthesis (OCCS)

3.1 Introduction

Refer to the OCCS chapter of the **56F8300 Peripheral User Manual** for a full description of the OCCS. The material contained here identifies the specific features of the OCCS design. **Figure 3-1** shows the specific OCCS block diagram to reference from the OCCS chapter of the **56F8300 Peripheral User Manual**.

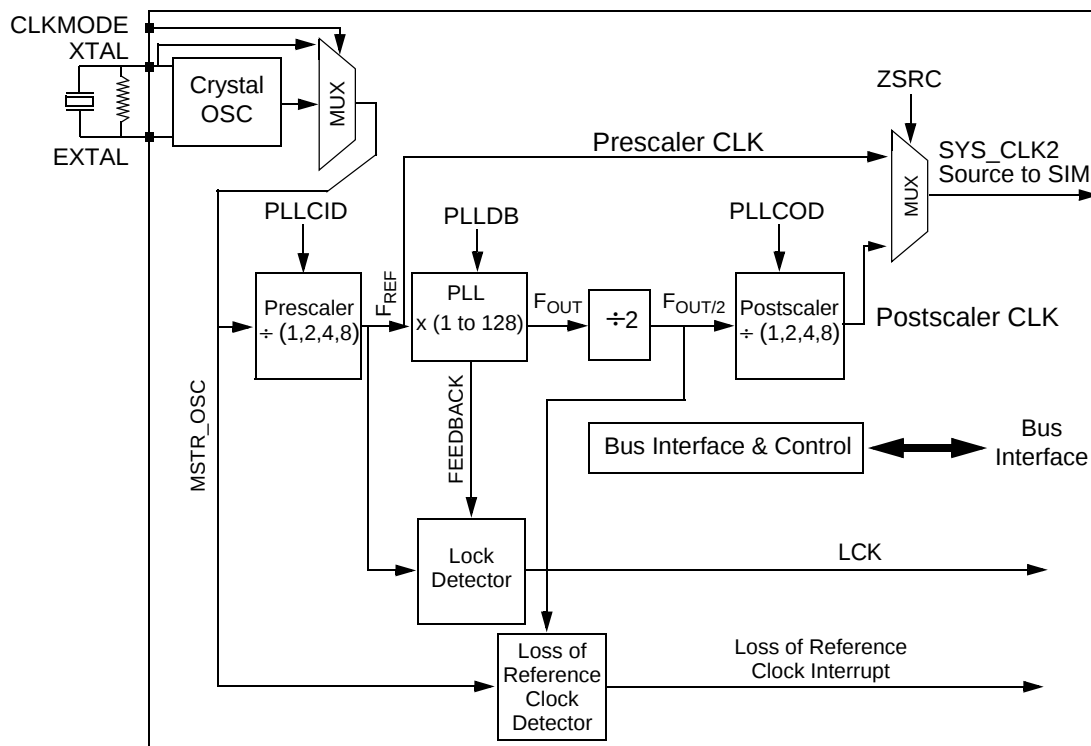


Figure 3-1 OCCS Block Diagram

3.2 External Clock Operation

The system clock can be derived from an external crystal, ceramic resonator, or an external system clock signal. To generate a reference frequency using the internal oscillator, a reference crystal or ceramic resonator must be connected between the EXTAL and XTAL pins.

3.2.1 Crystal Oscillator

The internal oscillator is designed to interface with a parallel-resonant crystal resonator in the frequency range specified for the external crystal in **Table 10-15**. A recommended crystal oscillator circuit is shown in **Figure 3-2**. Follow the crystal supplier's recommendations when selecting a crystal, since crystal parameters determine the component values required to provide maximum stability and reliable start-up.

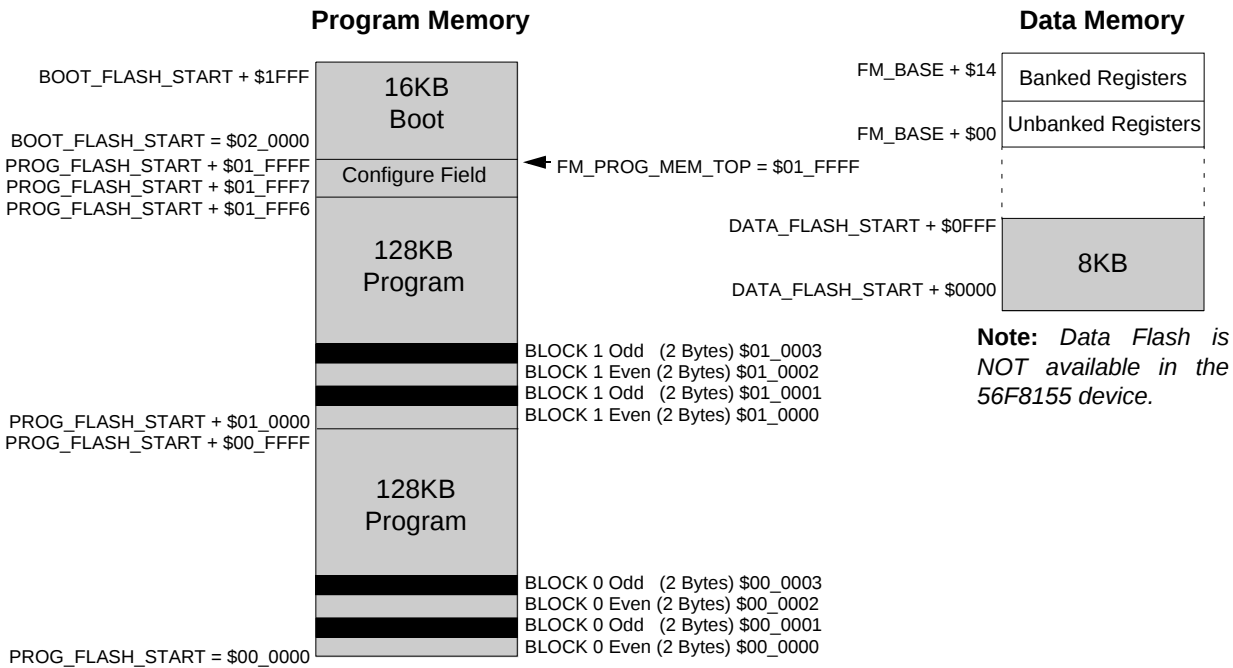


Figure 4-1 Flash Array Memory Maps

Table 4-7 shows the page and sector sizes used within each Flash memory block on the chip.

Note: Data Flash is NOT available on the 56F8155 device.

Table 4-7 Flash Memory Partitions

	Flash Size	Sectors	Sector Size	Page Size
Program Flash	256KB	16	8K x 16 bits	512 x 16 bits
Data Flash	8KB	16	256 x 16 bits	256 x 16 bits
Boot Flash	16KB	4	2K x 16 bits	256 x 16 bits

Please see **56F8300 Peripheral User Manual** for additional Flash information.

4.6 EOnCE Memory Map

Table 4-8 EOnCE Memory Map

Address	Register Acronym	Register Name
		Reserved

Table 4-12 Quad Timer B Registers Address Map (Continued)
(TMRB_BASE = \$00 F080)
Quad Timer B is NOT available in the 56F8155 device

Register Acronym	Address Offset	Register Description
TMRB3_CNTR	\$35	Counter Register
TMRB3_CTRL	\$36	Control Register
TMRB3_SCR	\$37	Status and Control Register
TMRB3_CMPLD1	\$38	Comparator Load Register 1
TMRB3_CMPLD2	\$39	Comparator Load Register 2
TMRB3_COMSCR	\$3A	Comparator Status and Control Register

Table 4-13 Quad Timer C Registers Address Map
(TMRC_BASE = \$00 F0C0)

Register Acronym	Address Offset	Register Description
TMRC0_CMP1	\$0	Compare Register 1
TMRC0_CMP2	\$1	Compare Register 2
TMRC0_CAP	\$2	Capture Register
TMRC0_LOAD	\$3	Load Register
TMRC0_HOLD	\$4	Hold Register
TMRC0_CNTR	\$5	Counter Register
TMRC0_CTRL	\$6	Control Register
TMRC0_SCR	\$7	Status and Control Register
TMRC0_CMPLD1	\$8	Comparator Load Register 1
TMRC0_CMPLD2	\$9	Comparator Load Register 2
TMRC0_COMSCR	\$A	Comparator Status and Control Register
		Reserved
TMRC1_CMP1	\$10	Compare Register 1
TMRC1_CMP2	\$11	Compare Register 2
TMRC1_CAP	\$12	Capture Register
TMRC1_LOAD	\$13	Load Register
TMRC1_HOLD	\$14	Hold Register
TMRC1_CNTR	\$15	Counter Register
TMRC1_CTRL	\$16	Control Register
TMRC1_SCR	\$17	Status and Control Register
TMRC1_CMPLD1	\$18	Comparator Load Register 1
TMRC1_CMPLD2	\$19	Comparator Load Register 2

**Table 4-17 Quadrature Decoder 0 Registers Address Map
(DEC0_BASE = \$00 F180)**

Register Acronym	Address Offset	Register Description
DEC0_DECCR	\$0	Decoder Control Register
DEC0_FIR	\$1	Filter Interval Register
DEC0_WTR	\$2	Watchdog Timeout Register
DEC0_POSD	\$3	Position Difference Counter Register
DEC0_POSDH	\$4	Position Difference Counter Hold Register
DEC0_REV	\$5	Revolution Counter Register
DEC0_REVH	\$6	Revolution Hold Register
DEC0_UPOS	\$7	Upper Position Counter Register
DEC0_LPOS	\$8	Lower Position Counter Register
DEC0_UPOSH	\$9	Upper Position Hold Register
DEC0_LPOSH	\$A	Lower Position Hold Register
DEC0_UIR	\$B	Upper Initialization Register
DEC0_LIR	\$C	Lower Initialization Register
DEC0_IMR	\$D	Input Monitor Register

**Table 4-18 Quadrature Decoder 1 Registers Address Map
(DEC1_BASE = \$00 F190)
*Quadrature Decoder 1 is NOT available in the 56F8155 device***

Register Acronym	Address Offset	Register Description
DEC1_DECCR	\$0	Decoder Control Register
DEC1_FIR	\$1	Filter Interval Register
DEC1_WTR	\$2	Watchdog Timeout Register
DEC1_POSD	\$3	Position Difference Counter Register
DEC1_POSDH	\$4	Position Difference Counter Hold Register
DEC1_REV	\$5	Revolution Counter Register
DEC1_REVH	\$6	Revolution Hold Register
DEC1_UPOS	\$7	Upper Position Counter Register
DEC1_LPOS	\$8	Lower Position Counter Register
DEC1_UPOSH	\$9	Upper Position Hold Register
DEC1_LPOSH	\$A	Lower Position Hold Register
DEC1_UIR	\$B	Upper Initialization Register

Table 4-38 FlexCAN Registers Address Map (Continued)
(FC_BASE = \$00 F800)
FlexCAN is NOT available in the 56F8155 device

Register Acronym	Address Offset	Register Description
FCMB10_DATA	\$96	Message Buffer 10 Data Register
		Reserved
FCMB11_CONTROL	\$98	Message Buffer 11 Control / Status Register
FCMB11_ID_HIGH	\$99	Message Buffer 11 ID High Register
FCMB11_ID_LOW	\$9A	Message Buffer 11 ID Low Register
FCMB11_DATA	\$9B	Message Buffer 11 Data Register
FCMB11_DATA	\$9C	Message Buffer 11 Data Register
FCMB11_DATA	\$9D	Message Buffer 11 Data Register
FCMB11_DATA	\$9E	Message Buffer 11 Data Register
		Reserved
FCMB12_CONTROL	\$A0	Message Buffer 12 Control / Status Register
FCMB12_ID_HIGH	\$A1	Message Buffer 12 ID High Register
FCMB12_ID_LOW	\$A2	Message Buffer 12 ID Low Register
FCMB12_DATA	\$A3	Message Buffer 12 Data Register
FCMB12_DATA	\$A4	Message Buffer 12 Data Register
FCMB12_DATA	\$A5	Message Buffer 12 Data Register
FCMB12_DATA	\$A6	Message Buffer 12 Data Register
		Reserved
FCMB13_CONTROL	\$A8	Message Buffer 13 Control / Status Register
FCMB13_ID_HIGH	\$A9	Message Buffer 13 ID High Register
FCMB13_ID_LOW	\$AA	Message Buffer 13 ID Low Register
FCMB13_DATA	\$AB	Message Buffer 13 Data Register
FCMB13_DATA	\$AC	Message Buffer 13 Data Register
FCMB13_DATA	\$AD	Message Buffer 13 Data Register
FCMB13_DATA	\$AE	Message Buffer 13 Data Register
		Reserved
FCMB14_CONTROL	\$B0	Message Buffer 14 Control / Status Register
FCMB14_ID_HIGH	\$B1	Message Buffer 14 ID High Register
FCMB14_ID_LOW	\$B2	Message Buffer 14 ID Low Register
FCMB14_DATA	\$B3	Message Buffer 14 Data Register
FCMB14_DATA	\$B4	Message Buffer 14 Data Register

Table 5-2 Interrupt Priority Encoding

IPIC_LEVEL[1:0] ¹	Current Interrupt Priority Level	Required Nested Exception Priority
01	Priority 0	Priorities 1, 2, 3
10	Priority 1	Priorities 2, 3
11	Priorities 2 or 3	Priority 3

1. See IPIC field definition in [Part 5.6.30.2](#)

5.3.3 Fast Interrupt Handling

Fast interrupts are described in the DSP56800E Reference Manual. The interrupt controller recognizes fast interrupts before the core does.

A fast interrupt is defined (to the ITCN) by:

1. Setting the priority of the interrupt as level 2, with the appropriate field in the IPR registers
2. Setting the FIMn register to the appropriate vector number
3. Setting the FIVALn and FIVAHn registers with the address of the code for the fast interrupt

When an interrupt occurs, its vector number is compared with the FIM0 and FIM1 register values. If a match occurs, and it is a level 2 interrupt, the ITCN handles it as a fast interrupt. The ITCN takes the vector address from the appropriate FIVALn and FIVAHn registers, instead of generating an address that is an offset from the VBA.

The core then fetches the instruction from the indicated vector address and if it is not a JSR, the core starts its fast interrupt handling.

It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.1.4 Reserved—Bits 9–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.2 Interrupt Priority Register 1 (IPR1)

Base + \$1	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	RX_REG IPL		TX_REG IPL		TRBUF IPL	
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-4 Interrupt Priority Register 1 (IPR1)

5.6.2.1 Reserved—Bits 15–6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.2.2 EOnCE Receive Register Full Interrupt Priority Level (RX_REG IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.2.3 EOnCE Transmit Register Empty Interrupt Priority Level (TX_REG IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2

5.6.7.1 Timer C, Channel 0 Interrupt Priority Level (TMRC0 IPL)— Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.2 Timer D, Channel 3 Interrupt Priority Level (TMRD3 IPL)— Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.3 Timer D, Channel 2 Interrupt Priority Level (TMRD2 IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.4 Timer D, Channel 1 Interrupt Priority Level (TMRD1 IPL)— Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.5 Timer B, Channel 0 Interrupt Priority Level (TMRB0 IPL)—Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.6 Timer C, Channel 3 Interrupt Priority Level (TMRC3 IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.7 Timer C, Channel 2 Interrupt Priority Level (TMRC2 IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.8 Timer C, Channel 1 Interrupt Priority Level (TMRC1 IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9 Interrupt Priority Register 8 (IPR8)

Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	SCI0_RCV IPL		SCI0_RERR IPL		0	0	SCI0_TIDL IPL		SCI0_XMIT IPL		TMRA3 IPL		TMRA2 IPL		TMRA1 IPL	
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-11 Interrupt Priority Register 8 (IPR8)

5.6.9.1 SCI0 Receiver Full Interrupt Priority Level (SCI0_RCV IPL)— Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.2 SCI0 Receiver Error Interrupt Priority Level (SCI0_RERR IPL)— Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.3 Reserved—Bits 11–10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.9.4 SCI0 Transmitter Idle Interrupt Priority Level (SCI0_TIDL IPL)— Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.5 SCI0 Transmitter Empty Interrupt Priority Level (SCI0_XMIT IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.16 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

Base + \$F	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	FAST INTERRUPT 1 VECTOR ADDRESS LOW															
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-18 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

5.6.16.1 Fast Interrupt 1 Vector Address Low (FIVAL1)—Bits 15–0

The lower 16 bits of vector address are used for Fast Interrupt 1. This register is combined with FIVAH1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.17 Fast Interrupt 1 Vector Address High Register (FIVAH1)

Base + \$10	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	FAST INTERRUPT 1 VECTOR ADDRESS HIGH				
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-19 Fast Interrupt 1 Vector Address High Register (FIVAH1)

5.6.17.1 Reserved—Bits 15–5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.17.2 Fast Interrupt 1 Vector Address High (FIVAH1)—Bits 4–0

The upper five bits of vector address are used for Fast Interrupt 1. This register is combined with FIVAL1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.18 IRQ Pending 0 Register (IRQP0)

Base + \$11	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	PENDING [16:2]															1
Write																
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 5-20 IRQ Pending 0 Register (IRQP0)

5.6.18.1 IRQ Pending (PENDING)—Bits 16–2

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

Base + \$2	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	FIELD															
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-5 SIM Software Control Register 0 (SIM_SCR0)

6.5.3.1 Software Control Data 1 (FIELD)—Bits 15–0

This register is reset only by the Power-On Reset (POR). It has no part-specific functionality and is intended for use by a software developer to contain data that will be unaffected by the other reset sources (RESET pin, software reset, and COP reset).

6.5.4 Most Significant Half of JTAG ID (SIM_MSH_ID)

This read-only register displays the most significant half of the JTAG ID for the chip. This register reads \$01F4.

Base + \$6	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	1	1	1	1	1	0	1	0	0
Write																
RESET	0	0	0	0	0	0	0	1	1	1	1	1	0	1	0	0

Figure 6-6 Most Significant Half of JTAG ID (SIM_MSH_ID)

6.5.5 Least Significant Half of JTAG ID (SIM_LSH_ID)

This read-only register displays the least significant half of the JTAG ID for the chip. This register reads \$601D.

Base + \$7	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	1	1	0	0	0	0	0	0	0	0	1	1	1	0	1
Write																
RESET	0	1	1	0	0	0	0	0	0	0	0	1	1	1	0	1

Figure 6-7 Least Significant Half of JTAG ID (SIM_LSH_ID)

6.5.6 SIM Pullup Disable Register (SIM_PUDR)

Most of the pins on the chip have on-chip pullup resistors. Pins which can operate as GPIO can have these resistors disabled via the GPIO function. Non-GPIO pins can have their pullups disabled by setting the appropriate bit in this register. Disabling pullups is done on a peripheral-by-peripheral basis (for pins not muxed with GPIO). Each bit in the register (see [Figure 6-8](#)) corresponds to a functional group of pins. See

Table 2-2 to identify which pins can deactivate the internal pullup resistor.

Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	PWMA1	CAN	EMI_MODE	$\overline{\text{RESET}}$	IRQ	XBOOT	PWMB	PWMA0	0	CTRL	0	JTAG	0	0	0
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-8 SIM Pullup Disable Register (SIM_PUDR)

6.5.6.1 Reserved—Bit 15

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.6.2 PWMA1—Bit 14

This bit controls the pullup resistors on the FAULTA3 pin.

6.5.6.3 CAN—Bit 13

This bit controls the pullup resistors on the CAN_RX pin.

6.5.6.4 EMI_MODE—Bit 12

This bit controls the pullup resistors on the EMI_MODE pin

Note: In this package, this input pin is double-bonded with the adjacent V_{SS} pin and this bit should be changed to a 1 in order to reduce power consumption.

6.5.6.5 $\overline{\text{RESET}}$ —Bit 11

This bit controls the pullup resistors on the $\overline{\text{RESET}}$ pin.

6.5.6.6 IRQ—Bit 10

This bit controls the pullup resistors on the $\overline{\text{IRQA}}$ and $\overline{\text{IRQB}}$ pins.

6.5.6.7 XBOOT—Bit 9

This bit controls the pullup resistors on the EXTBOOT pin.

Note: In this package, this input pin is double-bonded with the adjacent V_{SS} pin and this bit should be changed to a 1 in order to reduce power consumption.

6.5.6.8 PWMB—Bit 8

This bit controls the pullup resistors on the FAULTB0, FAULTB1, FAULTB2, and FAULTB3 pins.

6.5.6.9 PWMA0—Bit 7

This bit controls the pullup resistors on the FAULTA0, FAULTA1, and FAULTA2 pins.

of security. When Flash security mode is enabled in accordance with the method described in the Flash Memory module specification, the device will disable the core EOnCE debug capabilities. Normal program execution is otherwise unaffected.

7.2 Flash Access Blocking Mechanisms

The 56F8355/56F8155 have several operating functional and test modes. Effective Flash security must address operating mode selection and anticipate modes in which the on-chip Flash can be compromised and read without explicit user permission. Methods to block these are outlined in the next subsections.

7.2.1 Forced Operating Mode Selection

At boot time, the SIM determines in which functional modes the device will operate. These are:

- Unsecured Mode
- Secure Mode (EOnCE disabled)

When Flash security is enabled as described in the Flash Memory module specification, the device will disable the EOnCE debug interface.

7.2.2 Disabling EOnCE Access

On-chip Flash can be read by issuing commands across the EOnCE port, which is the debug interface for the 56800E core. The TRST, TCLK, TMS, TDO, and TDI pins comprise a JTAG interface onto which the EOnCE port functionality is mapped. When the device boots, the chip-level JTAG TAP (Test Access Port) is active and provides the chip's boundary scan capability and access to the ID register.

Proper implementation of Flash security requires that no access to the EOnCE port is provided when security is enabled. The 56800E core has an input which disables reading of internal memory via the JTAG/EOnCE. The FM sets this input at reset to a value determined by the contents of the FM security bytes.

7.2.3 Flash Lockout Recovery

If a user inadvertently enables Flash security on the device, a built-in lockout recovery mechanism can be used to reenables access to the device. This mechanism completely reases all on-chip Flash, thus disabling Flash security. Access to this recovery mechanism is built into CodeWarrior via an instruction in memory configuration (.cfg) files. Add, or uncomment the following configuration command:

unlock_flash_on_connect 1

For more information, please see **CodeWarrior MC56F83xx/DSP5685x Family Targeting Manual**.

The LOCKOUT_RECOVERY instruction has an associated 7-bit Data Register (DR) that is used to control the clock divider circuit within the FM module. This divider, FM_CLKDIV[6:0], is used to control the period of the clock used for timed events in the FM erase algorithm. This register must be set with appropriate values before the lockout sequence can begin. Refer to the JTAG section of the **56F8300 Peripheral User Manual** for more details on setting this register value.

Table 10-1 Absolute Maximum Ratings

($V_{SS} = V_{SSA_ADC} = 0$)

Characteristic	Symbol	Notes	Min	Max	Unit
Supply voltage	V_{DD_IO}		- 0.3	4.0	V
ADC Supply Voltage	V_{DDA_ADC}, V_{REFH}	V_{REFH} must be less than or equal to V_{DDA_ADC}	- 0.3	4.0	V
Oscillator / PLL Supply Voltage	$V_{DDA_OSC_PLL}$		- 0.3	4.0	V
Internal Logic Core Supply Voltage	V_{DD_CORE}	OCR_DIS is High	- 0.3	3.0	V
Input Voltage (digital)	V_{IN}	Pin Groups 1, 2, 5, 6, 9, 10	-0.3	6.0	V
Input Voltage (analog)	V_{INA}	Pin Groups 11, 12, 13	-0.3	4.0	V
Output Voltage	V_{OUT}	Pin Groups 1, 2, 3, 4, 5, 6, 7, 8	-0.3	4.0 6.0 ¹	V
Output Voltage (open drain)	V_{OD}	Pin Group 4	-0.3	6.0	V
Ambient Temperature (Automotive)	T_A		-40	125	°C
Ambient Temperature (Industrial)	T_A		-40	105	°C
Junction Temperature (Automotive)	T_J		-40	150	°C
Junction Temperature (Industrial)	T_J		-40	125	°C
Storage Temperature (Automotive)	T_{STG}		-55	150	°C
Storage Temperature (Industrial)	T_{STG}		-55	150	°C

1. If corresponding GPIO pin is configured as open drain.

Note: Pins in *italics* are NOT available on the 56F8155 device.

Pin Group 1: TXD0-1, RXD0-1, $\overline{SS0}$, MISO0, MOSI0

Pin Group 2: PHASEA0, *PHASEA1*, PHASEB0, *PHASEB1*, INDEX0, *INDEX1*, HOME0, *HOME1*, ISB0-2, *ISA0-2*, TD2-3, TC0-1, TDO, SCLK0

Pin Group 3: $\overline{RST0}$, TDO

Pin Group 4: CAN_TX

Pin Group 5: D0-15, GPIOD0-5

Pin Group 6: A8-15, GPIOB0-4, *TD0-1*

Pin Group 7: CLK0

Pin Group 8: *PWMA0-5*, PWMB0-5

Pin Group 9: $\overline{IRQA}$, $\overline{IRQB}$, $\overline{RESET}$, EXTBOOT, $\overline{TRST}$, TMS, TDI, CAN_RX, EMI_MODE, *FAULTA0-3*, FAULTB0-3

Pin Group 10: TCK

Pin Group 11: XTAL, EXTAL

Pin Group 12: ANA0-7, ANB0-7

Pin Group 13: OCR_DIS, CLKMODE

Table 10-15 Crystal Oscillator Parameters

Characteristic	Symbol	Min	Typ	Max	Unit
Bias Current, high-drive mode	I_{BIASH}	—	250	290	μA
Bias Current, low-drive mode	I_{BIASL}	—	80	110	μA
Quiescent Current, power-down mode	I_{PD}	—	0	1	μA

10.8 Reset, Stop, Wait, Mode Select, and Interrupt Timing

Table 10-16 Reset, Stop, Wait, Mode Select, and Interrupt Timing^{1,2}

Characteristic	Symbol	Typical Min	Typical Max	Unit	See Figure
Minimum $\overline{RESET}$ Assertion Duration	t_{RA}	16T	—	ns	10-5
Edge-sensitive Interrupt Request Width	t_{IRW}	1.5T	—	ns	10-6
$\overline{IRQA}$, $\overline{IRQB}$ Assertion to General Purpose Output Valid, caused by first instruction execution in the interrupt service routine	t_{IG}	18T	—	ns	10-7
	$t_{IG} - \text{FAST}$	14T	—		
$\overline{IRQA}$ Width Assertion to Recover from Stop State ³	t_{IW}	1.5T	—	ns	10-9

1. In the formulas, T = clock cycle. For an operating frequency of 60MHz, T = 16.67ns. At 8MHz (used during Reset and Stop modes), T = 125ns.
2. Parameters listed are guaranteed by design.
3. The interrupt instruction fetch is visible on the pins only in Mode 3.

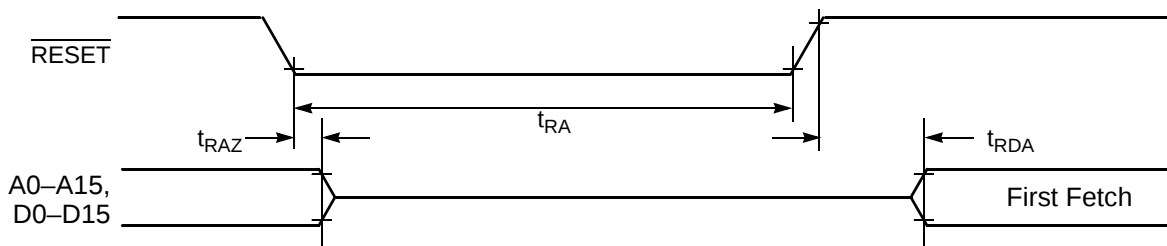


Figure 10-5 Asynchronous Reset Timing

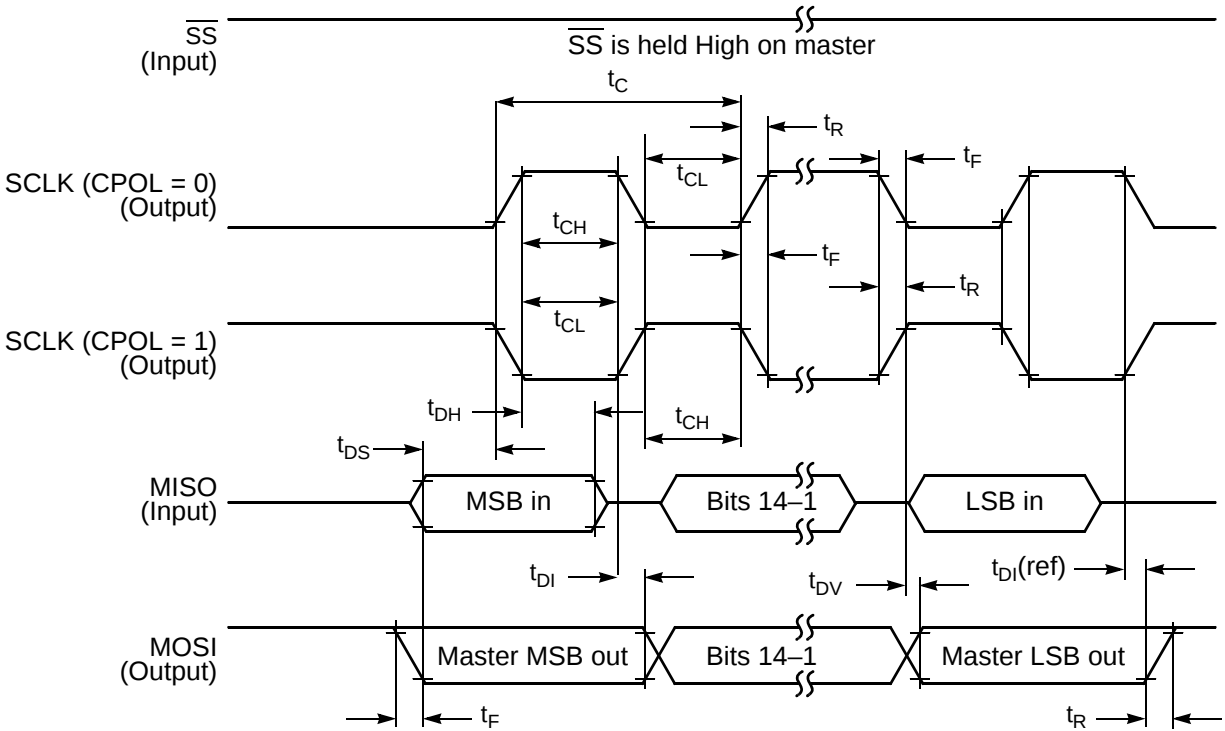


Figure 10-10 SPI Master Timing (CPHA = 0)

Ψ_{JT} = Thermal characterization parameter ($^{\circ}\text{C}/\text{W}$)

P_D = Power dissipation in package (W)

The thermal characterization parameter is measured per JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

When heat sink is used, the junction temperature is determined from a thermocouple inserted at the interface between the case of the package and the interface material. A clearance slot or hole is normally required in the heat sink. Minimizing the size of the clearance is important to minimize the change in thermal performance caused by removing part of the thermal interface to the heat sink. Because of the experimental difficulties with this technique, many engineers measure the heat sink temperature and then back-calculate the case temperature using a separate measurement of the thermal resistance of the interface. From this case temperature, the junction temperature is determined from the junction-to-case thermal resistance.

12.2 Electrical Design Considerations

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Use the following list of considerations to assure correct operation:

- Provide a low-impedance path from the board power supply to each V_{DD} pin on the device, and from the board ground to each V_{SS} (GND) pin
- The minimum bypass requirement is to place six 0.01–0.1 μF capacitors positioned as close as possible to the package supply pins. The recommended bypass configuration is to place one bypass capacitor on each of the V_{DD}/V_{SS} pairs, including V_{DDA}/V_{SSA} . Ceramic and tantalum capacitors tend to provide better performance tolerances.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{DD} and V_{SS} (GND) pins are less than 0.5 inch per capacitor lead
- Use at least a four-layer Printed Circuit Board (PCB) with two inner layers for V_{DD} and V_{SS}